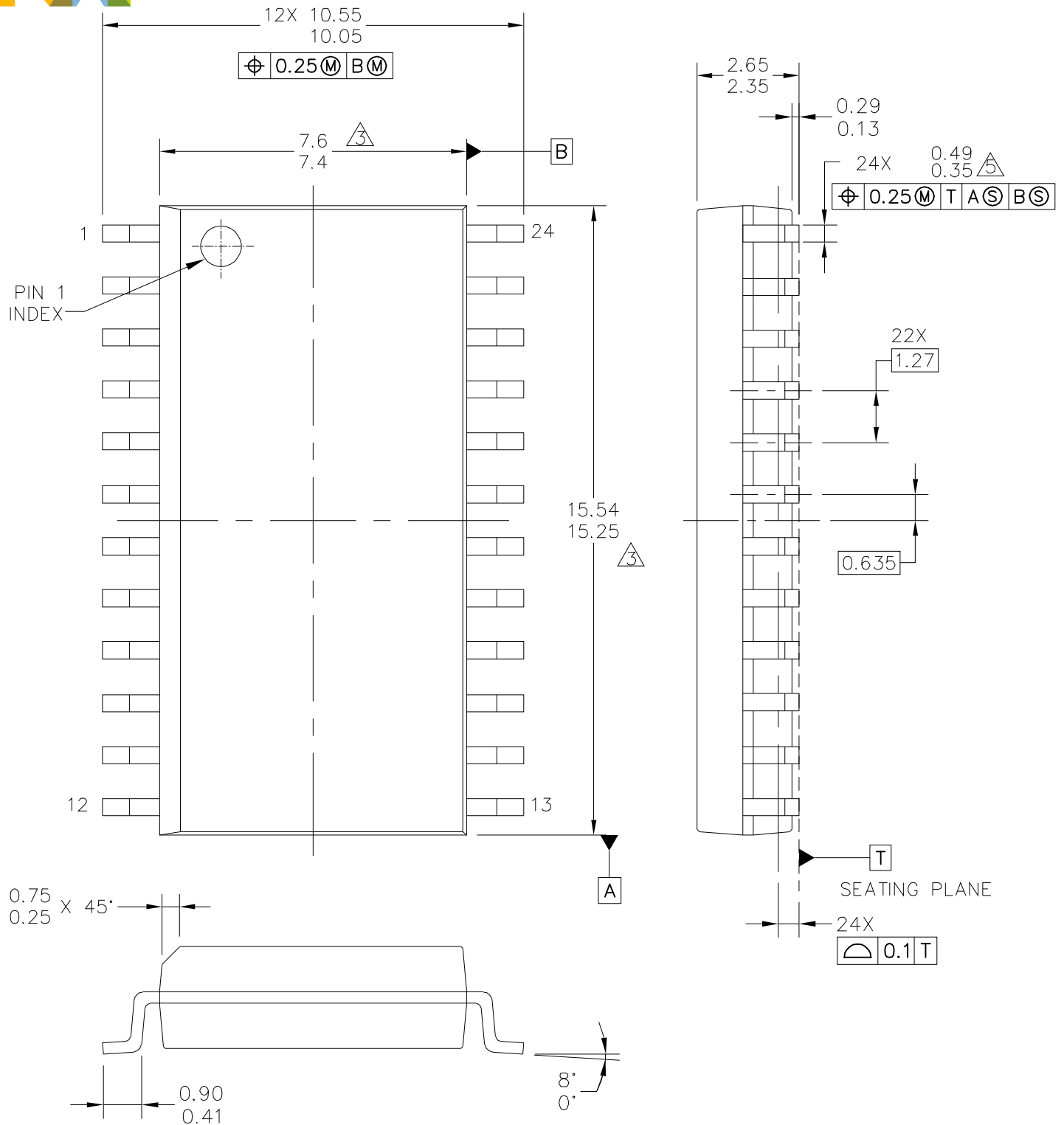




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TITLE: 24LD SOIC W/B, 1.27 PITCH 7.5 X 15.4 CASE-OUTLINE	DOCUMENT NO: 98ASB42344B REV: H	
	STANDARD: JEDEC MS-013 AD	
	SOT137-2	11 MAR 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

2. DIMENSIONS ARE IN MILLIMETERS.

△3. THIS DIMENSION DO NOT INCLUDE MOLD PROTRUSION.

4. MAXIMUM MOLD PROTRUSION 0.15(0.006) PER SIDE.

△5. THIS DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSION. ALLOWABLE DAM BAR PROTRUSION SHALL BE 0.13(0.005) TOTAL IN EXCESS OF THIS DIMENSION AT MAXIMUM MATERIAL CONDITION.

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